

THERMAL APPLICATIONS

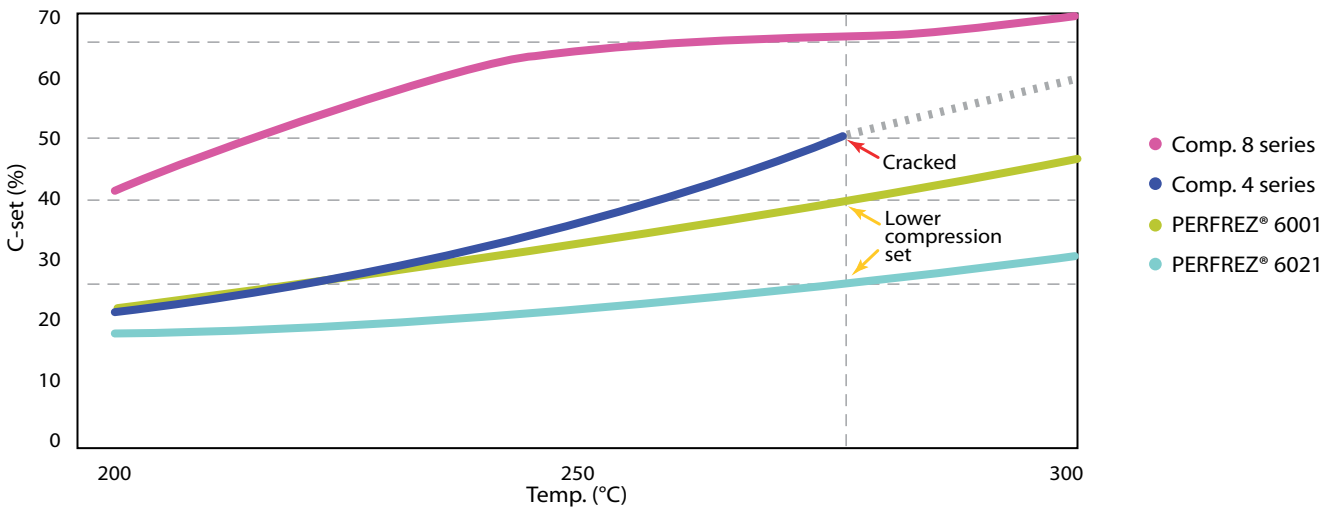
THERMAL APPLICATIONS

Applied Seals compounds are proven to have excellent thermal stability and maintain seal integrity at elevated temperatures often found in processes such as Oxidation, Diffusion, Annealing and RTP. Our ultra pure, highly engineered materials exhibit extremely low outgassing throughout thermal process temperature ranges and generate fewer particles in reaction chambers.



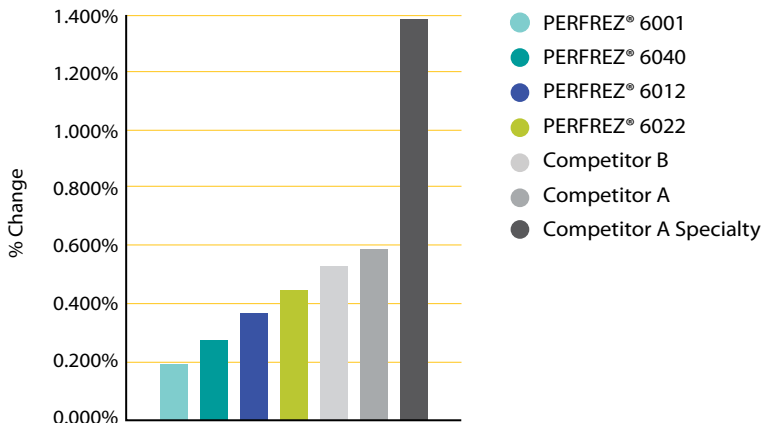
RTP FURNACE PERFORMANCE COMPRESSION SET COMPARISON

Excellent thermal stability shown throughout full range of process temperatures. Competitive materials show cracking at 300°C after 72 hours while PERFREZ® seals maintain their integrity across the full temperature range.



COMPETITIVE TGA PERFORMANCE ANALYSIS IN THERMAL APPLICATIONS

The following TGA (Thermo Gravimetric Analysis) analysis chart shows impressively low weight-loss, or out-gassing, performance for PERFREZ materials throughout their operating temperature range.



Test spec:
 1. Hold for 1.0 min at 50°C
 2. Heat from 50°C to 1000°C at 20°C/min.

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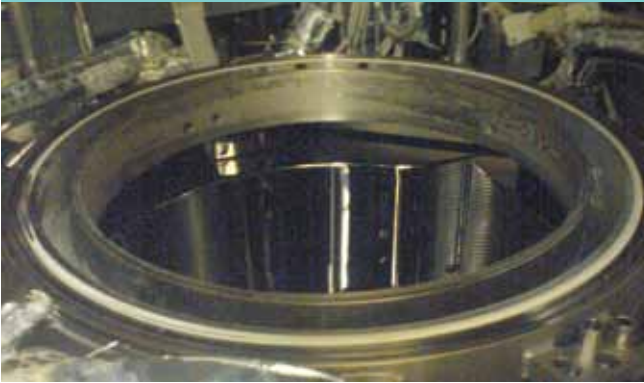
RTP FURNACE PERFORMANCE CASE STUDY

Process: RTP Furnace

Equipment: OTM-07 flange

Flange temp: 200°C to 300°C

RTP Furnace Environment



After Use: Slight burn areas



After Use: Material adhered to the quartz

